

Title (en)  
SEMICONDUCTOR WAFER LEVEL PACKAGE

Title (de)  
HALBLEITERVERPACKUNG AUF WAFEREBENE

Title (fr)  
BOITIER SUR TRANCHE (WLP) DE SEMICONDUCTEUR

Publication  
**EP 1216487 A1 20020626 (EN)**

Application  
**EP 00961925 A 20000915**

Priority  
• US 0025315 W 20000915  
• US 15440099 P 19990917

Abstract (en)  
[origin: WO0120671A1] A semiconductor wafer level package used to encapsulate a device fabricated on a semiconductor substrate wafer (11) before dicing of the wafer into individual chips. A cap wafer (16) may be bonded to the semiconductor substrate using a low temperature frit glass layer (14) as a bonding agent. The frit glass layer (14) is in direct contact with the device. A hermetic seal is formed by a combination of the semiconductor substrate wafer (11), the cap wafer (16) and the first glass layer (14). A second embodiment of the package (21) does not contain a cap wafer.

IPC 1-7  
**H01L 23/04**; H01L 23/10; H01L 21/56; H01L 23/29; H01L 21/52; H01L 21/54

IPC 8 full level  
**H01L 21/52** (2006.01); **H01L 21/54** (2006.01); **H01L 21/56** (2006.01); **H01L 23/04** (2006.01); **H01L 23/10** (2006.01); **H01L 23/29** (2006.01)

CPC (source: EP)  
**H01L 21/52** (2013.01); **H01L 21/54** (2013.01); **H01L 21/56** (2013.01); **H01L 23/04** (2013.01); **H01L 23/10** (2013.01); **H01L 23/291** (2013.01);  
**H01L 2924/0002** (2013.01)

Citation (search report)  
See references of WO 0120671A1

Cited by  
CN1295508C

Designated contracting state (EPC)  
DE FR GB IT

DOCDB simple family (publication)  
**WO 0120671 A1 20010322**; AU 7381200 A 20010417; EP 1216487 A1 20020626

DOCDB simple family (application)  
**US 0025315 W 20000915**; AU 7381200 A 20000915; EP 00961925 A 20000915